

Specification for Approval

Customer:	
•	

Model Name:

Si	upplier Approv	Customer approval	
R&D Designed	R&D Approved	QC Approved	
Peter	Peng Jun		



2018-06-28

Revision Record

REV NO.	REV DATE	CONTENTS	Note
A	2018-06-28	NEW ISSUE	



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1. Scope

This specification defines general provisions as well as inspection standards for TFT module supplied by AMSON electronics.

If the event of unforeseen problem or unspecified items may occur, naturally shall negotiate and agree to solution

2. General Information

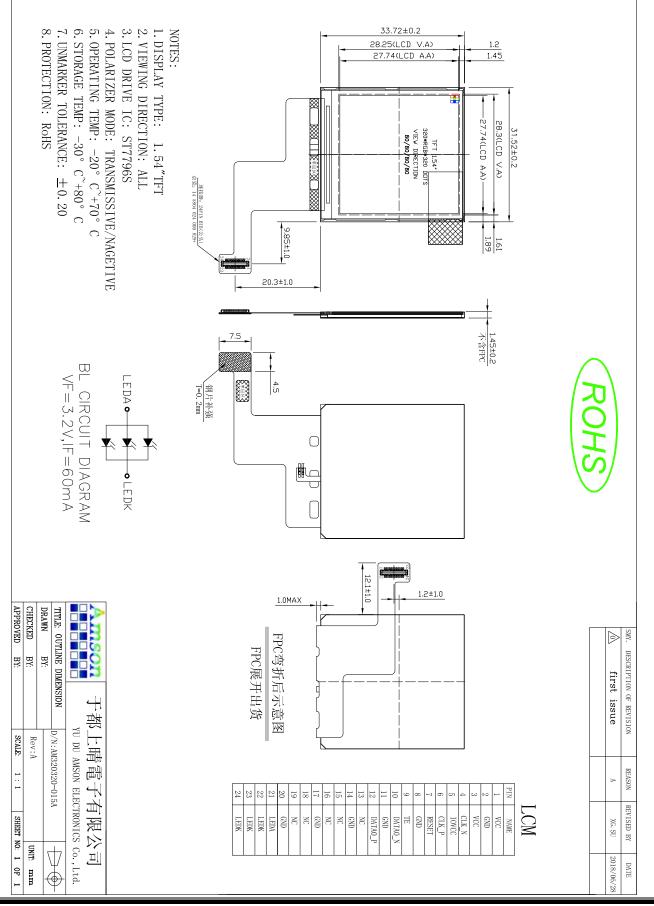
ITEM	STANDARD VALUES	UNITS
LCD type	1.54"TFT	
Dot arrangement	320(RGB)×320	dots
Color filter array	RGB vertical stripe	
Display mode	IPS / Transmissive / Normally Black	
Viewing Direction	80/80/80/80	
Driver IC	ST7796S	
Module size	31.52(W)×33.72(H)×1.45(T)	mm
Active area	27.744(W)×27.744(H)	mm
Dot pitch	0.0867(W)×0. 0867(H)	mm
Interface	MIPI-DSI	
Operating temperature	-20 ~ +70	°C
Storage temperature	-30 ~ +80	°C
Back Light	3 White LED	
Weight	TBD	g



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3. External Dimensions



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4. Interface Description

PIN NO.	PIN NAME	DESCRIPTION
1	VCC	System power supply.
2	GND	System power ground.
3	VCC	System power supply.
4	CLK_N	DSI-CLK- differential clock signals.
5	IOVCC	System power supply.
6	CLK_P	DSI-CLK+ differential clock signals.
7	RESET	Reset signal input terminal, active at 'L'.
8	GND	System power ground.
9	TE	Tearing effect output. If not used, please open this pin.
10	DATA0_N	DSI-DATA- differential data signals.
11	GND	System power ground.
12	DATA0_P	DSI-DATA+ differential data signals.
13	NC	NC.
14	GND	System power ground.
15	NC	NC.
16	NC	NC.
17	GND	System power ground.
18	NC	NC.
19	NC	NC.
20	GND	System power ground.
21	LEDA	Power supply for backlight anode input terminal.
22	LEDK	Power supply for backlight cathode input terminal.
23	LEDK	Power supply for backlight cathode input terminal.
24	LEDK	Power supply for backlight cathode input terminal.



5. Absolute Maximum Ratings

Item	Symbol	Min.	Max.	Unit
Logic Supply Voltage	IOVCC	-0.3	4.6	V
Analog Supply Voltage	VCC	-0.3	4.6	V
Input Voltage	Vin	-0.3	IOVCC+0.3	V
Operating Temperature	Тор	-20	70	°C
Storage Temperature	Тѕт	-30	80	°C
Storage Humidity	HD	20	90	%RH

6. DC Characteristics

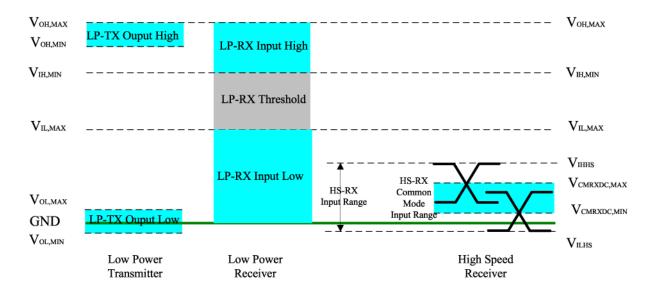
6.1DC Characteristics for Panel and CTP Driving

ltem	Symbol	Min.	Тур.	Max.	Unit	Remark
Logic Supply Voltage	IOVCC	1.65	-	3.3	V	-
Analog Supply Voltage	VCC	2.5	-	3.3	V	-
Input High Voltage	V _{IH}	0.7IOVCC	-	IOVCC	V	Digital input pins
Input Low Voltage	V _{IL}	GND	-	0.3IOVCC	V	Digital input pins
Output High Voltage	V _{OH}	0.8IOVCC	-	IOVCC	V	Digital output pins
Output Low Voltage	V _{OL}	GND	-	0.2IOVCC	V	Digital output pins
I/O Leak Current	ILI	-1.0	-	1.0	uA	-



6.2DC characteristics for MIPI DSI

MIPI Signaling Voltage Levels



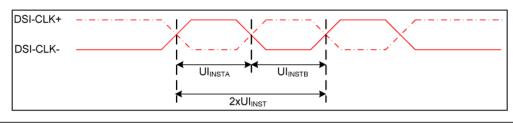
MIPI DC characteristics

Parameter	Symbol		Specification		Unit
	Symbol	MIN	ТҮР	MAX	Unit
Operation	Voltage for I	MIPI Receive	r		
Low power mode operating voltage	Vlph	1.1	1.2	1.3	V
MIPI Characteristics for High Speed Receiver					
Single-ended input low voltage	V ILHS	-40	-	-	mV
Single-ended input high voltage	V IHHS	-	-	460	mV
Common-mode voltage	VCMRXDC	70	-	330	mV
Differential input impedance	ZID	80	100	125	ohm
MIPI Charac	teristics for L	ow Power M	ode		
Pad signal voltage range	VI	-50	-	1350	mV
Logic 0 input threshold	VIL	0	-	550	mV
Logic 1 input threshold	Vih	880	-	1350	mV
Output low level	Vol	-50	-	50	mV
Output high level	Vон	1.1	1.2	1.3	V



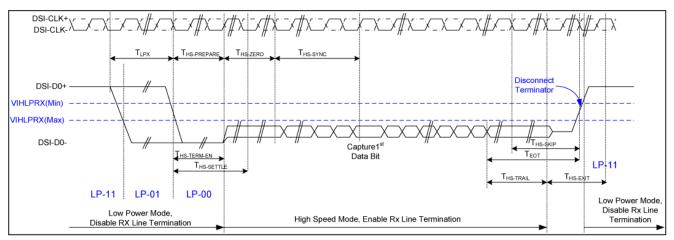
7. Timing Characteristics

7.1 MIPI Timing Characteristics High Speed Mode – Clock Channel Timing



Signal	Symbol	Parameter	MIN	MAX	Unit	Description
DSI-DATA_P/N	2xUI INST	Double UI instantaneous	4	25	ns	
DSI-DATA_P/N	UI INSTA ,UI INSTB	UI instantaneous Half	2	12.5	ns	

High-Speed Data Transmission

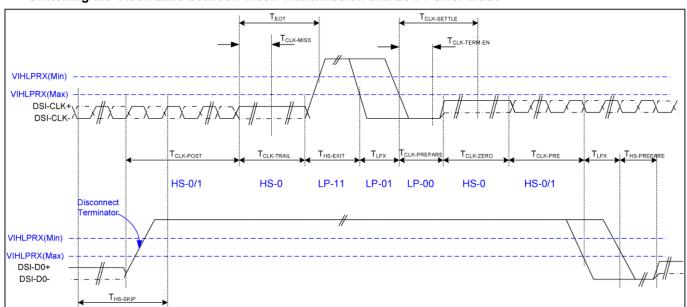


Parameter	Symbol	MIN	ТҮР	MAX	Unit
Time to drive LP-00 to prepare for HS transmission	THS-PREPARE	40+4UI		85+6UI	ns
Time from start of t HS-TRAIL or t CLK-TRAIL period to start of LP-11 state	Теот			105+12UI	ns
Time to enable data receiver line termination measured from when Dn crosses VILMAX	THS-TERM-EN			35+4UI	ns
Time to drive flipped differential state after last payload data bit of a HS transmission	Ths-trail	60+4UI			ns
Time-out at RX to ignore transition period of EoT	T _{HS-SKIP}	40		55+4UI	ns
Time to drive LP-11 after HS burst	THS-EXIT	100			ns
Length of any Low-Power state period	TLPX	50			ns
Sync sequence period	Тнѕ-ѕүмс		8UI		ns
Minimum lead HS-0 drive period before the Sync sequence	Ths-zero	105+6UI			ns



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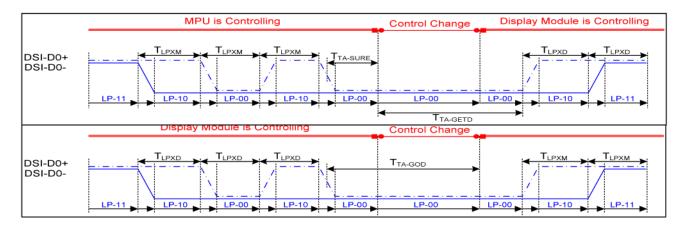
Switching the Clock Lane between Clock Transmission and Low-Power Mode



Parameter	Symbol	MIN	ТҮР	MAX	Unit
Time that the transmitter shall continue sending HS clock after the last associated Data	T CLK-POST	60+52UI			ns
Lane has transitioned to LP mode	I CLK-POST	00+5201			115
Detection time that the clock has stopped toggling	T CLK-MISS			60	ns
Time to drive LP-00 to prepare for HS clock transmission	T CLK-PREPARE	38		95	ns
Minimum load HS 0 drive period before starting Cleak	T CLK-PREPARE	200			
Minimum lead HS-0 drive period before starting Clock	+T CLK-ZERO	300			ns
Time to enable Clock Lane receiver line termination measured from when Dn cross	т			38	
VIL,MAX	T HS-TERM-EN			30	ns
Minimum time that the HS clock must be set prior to any associated date lane beginning	тт	8			u
the transmission from LP to HS mode	T CLK-PRE	0			
Time to drive HS differential state after last payload clock bit of a HS transmission burst	T CLK-TRAIL	60			ns



Bus Turnaround Procedure

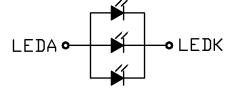


Parameter	Symbol	MIN	ТҮР	MAX	Unit
Length of any Low-Power state period : Master side	Tlpx	50		75	ns
Length of any Low-Power state period : Slave side	Tlpx	47.5	50	52.5	ns
Ratio of T_{LPX} (MASTER)/ T_{LPX} (SLAVE) between Master and Slave side	Ratio TLPX	2/3		3/2	
Time-out before new TX side start driving	T TA-SURE	TLPX		2 Tlpx	ns
Time to drive LP-00 by new TX	T ta-get		5 Tlpx		ns
Time to drive LP-00 after Turnaround Request	T ta-go		4 Tlpx		ns



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8. Backlight Characteristic



BL CIRCUIT DIAGRAM VF=3.2V,IF=60mA

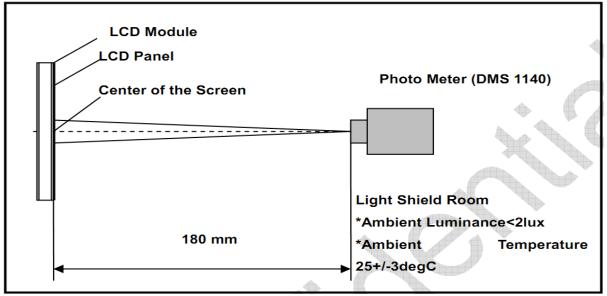
ltem	Symbol	MIN	TYP	MAX	UNIT	Test Condition
Supply Voltage	Vf	2.9	3.2	3.5	V	lf=60mA
Supply Current	lf	-	60	75	mA	-
Luminous Intensity for LCM	-	300	350	-	Cd/m ²	lf=60mA
Life Time	-	20000	-	-	Hr	lf=60mA
Backlight Color	White					



9. Optical Characteristics

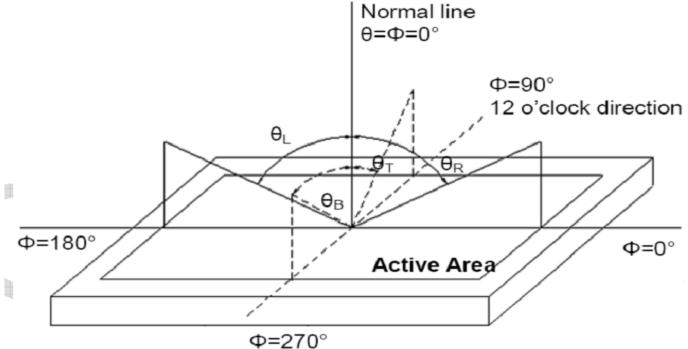
Item	Condition	S	Min.	Тур.	Max.	Unit	Note	
	Horizontal	θL		80	-			
Viewing Angle	HOHZOHIAI	θr		80	-			
(CR>10)	Vortical	θτ		80	-	degree	(1),(2),(6)	
	Vertical	θв		80	-			
Contrast Ratio	Center		-	900	-	-	(1),(3),(6)	
Response Time	Rising		-	35	50	ms	(1) (4) (6)	
	Falling		-	35	50	ms	(1),(4),(6)	
	Red x			TBD		-		
	Red y			TBD		-		
	Green x			TBD		-		
CF Color	Green y			TBD		-	(1) (6)	
Chromaticity (CIE1931)	Blue x		Тур.	TBD	Тур.	-	(1), (6)	
	Blue y		-0.05	TBD	+0.05	-		
	White x			TBD		-		
	White y			TBD		-		
NTSC	CIE1931		-	55.3	-	%	(1),(6)	

Note (1) Measurement Setup: The LCD module should be stabilized at given temp. 25°C for 15 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting backlight for 15 minutes in a windless room.





Note (2) Definition of Viewing Angle



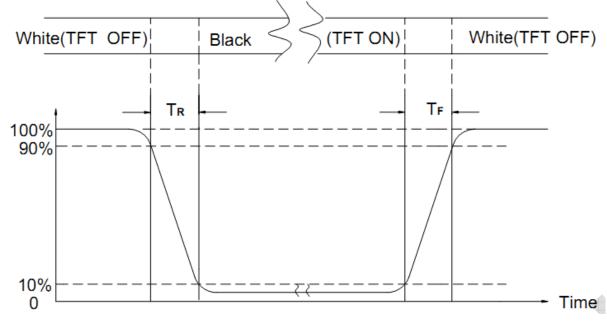
Note (3) Definition of Contrast Ratio (CR)

The contrast ratio can be calculated by the following expression Contrast Datia (CD) = 1.62 / 1.0

Contrast Ratio (CR) = L63 / L0

L63: Luminance of gray level 63, L0: Luminance of gray level 0

Note (4) Definition of response time



- Note (5) Definition of Transmittance (Module is without signal input) Transmittance = Center Luminance of LCD / Center Luminance of Back Light x 100%
- Note (6) Definition of color chromaticity (CIE1931)

Color coordinates measured at the center point of LCD



10. Reliability Test Conditions And Methods

NO.	TEST ITEMS	TEST CONDITION	INSPECTION AFTER TEST
1	High Temperature Storage	80°C±2°C×96Hours	
2	Low Temperature Storage	-30°C±2°C×96Hours	
3	High Temperature Operating	70°C±2°C×96Hours	
4	Low Temperature Operating	-20°C±2°C×96Hours	Inspection after 2~4hours storage at room temperature, the samples
5	Temperature Cycle(Storage)	-20°C \longleftrightarrow 25°C \longleftrightarrow 70°C (30min) (5min) (30min) 1cycle Total 10cycle	should be free fromdefects:1, Air bubble in the LCD.2, Seal leak.3, Non-display.4, Missing segments.
6	Damp Proof Test (Storage)	50°C±5°C×90%RH×120Hours	5, Glass crack. 6, Current IDD is twice
Ø	Vibration Test	Frequency:10Hz~55Hz~10Hz Amplitude:1.5MM X,Y,Z direction for total 3hours (packing condition test will be tested by a carton)	higher than initial value. 7, The surface shall be free from damage. 8, The electric characteristic requirements shall be satisfied.
8	Drooping Test	Drop to the ground from 1M height one time every side of carton. (packing condition test will be tested by a carton)	
9	ESD Test	Voltage:±8KV,R:330Ω,C:150PF,Air Mode,10times	

REMARK:

1, The Test samples should be applied to only one test item.

2, Sample side for each test item is 5~10pcs.

3,For Damp Proof Test, Pure water(Resistance > $10M\Omega$)should be used.

4, In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part.

5, EL evaluation should be accepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has.

6, Failure Judgment Criterion: Basic Specification Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.



11. Inspection Standard

11.1 Incoming Inspection and Standard:

The below incoming inspection are applied to the TFT LCM Modules supplied by AMSON Optoelectronic Industry CO.,LTD. The customers should inspect the LCM within 14 days after receiving the goods. The result of inspection should be notified to the Seller in the writing copy promptly, if the customer do not send them within 14 days, the seller has the right to judge as acceptance of goods. The inspection lot size is treated as the quantity per shipment and per model. The sampling plan shall be inspected under MIL-STD015E in Level II by single sampling. The acceptable quality level (AQL) are categorized as below grades:

CRITICAL= 0.65%, MAJOR= 0.65%, MINOR= 1.5%

11.2 Inspection condition and Warranty policy:

The delivered LCM should be stored properly, ideally under climate-controlled environment at $25 (\pm 5)$ degree Celsius as well as $60\% (\pm 10)$ Relative Humidity. The LCM shall be inspected in the viewing angle of 45 degree from the four major angles (U/D/L/R) under the single fluorescent lamp of 20W (equal to 300 to 500 lux). For warranty, AMSON Optoelectronic Industry CO.,LTD. will provide 12 months of warranty period as standard, and provide the new replacement for the defective products which belong to the Seller's responsibility verified by the quality department.

11.3 Inspection Criteria:

Item No.	Inspection content	Judgement
11.3.1.1	Functional defects	No display, abnormal display, short circuit, missing line, off-contrast and chromaticity, Touch Panel non-function
11.3.1.2	Model mixed	Other model mixed

11.3.1 Critical defect (重度缺失)

11.3.2 Major defect: (主要缺失)

Item No.	Inspection content	Judgement
11.3.2.1	Product indication	Missing model no. and wrong model no. is indicated on the LCM.
11.3.2.2	Glass cracking	The LCD and touch panel glass crack or breakage
11.3.2.3	Missing component	The function component missing such as connector, cable, etc.



11.3.3 Minor defect (LCD) : (次要缺失)

Item No.	Inspection content	Judgement				
11.3.3.1	I1.3.3.1 Black/White spot Foreign particles Dust in the cell					
		Diameter	(mm)		Acceptable Q'ty	
		Φ ≦ 0	.1		Ignore	
		0.1 < Φ ≦	≦ 0.25	3	(Distance>5mm)	
		0.25 <	Φ		Not allowed	
11.3.3.2	Black/white line Black/white		Width (W ≦0.		Acceptable Q'ty Ignore	
	scratch	L≦ 5.0	0.03 <w< td=""><td>≦0.07</td><td>3</td><td></td></w<>	≦0.07	3	
			0.07 <	<w< td=""><td>Follow 11.3.3.1</td><td></td></w<>	Follow 11.3.3.1	
11.3.3.3	1.3.3.3 Polarizer Bubbles Dent on polarizer	Diameter (mm) Φ ≤ 0.2			Acceptable Q'ty Ignore	
		0.2 < Φ ≦ 0.5		2	2 (Distance>5mm)	
		0.5 < Φ		Not allowed		
11.3.3.4	Electrical Dot defect	ot Bright dot and Dark dot definition: Image: Constraint of the second secon				
		Inspection pattern: black, whit blue screen.				ınd
		Items		Acceptable Q'ty		
		Bright dot		N ≦	4 (Distance >5mm)	
		Dark dot		N ≦	4 (Distance >5mm)	



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11.3.3.5	Glass Defect- Corner chipping				
		Size(mm)	Judgement		
		X≦3mm, Y≦S ,	Accept		
		Z≦ T			
		(S= ITO length, T=Single glass thickness)			
11.3.3.6	Glass Defect- Side fragment	ct-			
		Size(mm)	Judgement		
		X≦2 mm, Y≦ border edo	ge Accept		
		Z≦T			
		(T= single glass thickne	ess)		

11.3.4 Minor defect (Touch Panel)

ltem No.	Inspection content	Judgement	
11.3.4.1	Scratch, dust, particles, foreign	Size (mm)	Acceptable Q'ty
	materials in "linear type"	W≦0.05mm, L≦10mm	Ignore
	0.05mm <w 0.07mm,="" l="" ≦="" ≦<br="">10mm</w>	3	
		W>0.07mm	Reject
11.3.4.2	Scratch, dust,		
	particles, foreign	Diameter (mm)	Acceptable Q'ty
materials in "round type"	Φ≦ 0.25mm	Ignore	
		0.25mm<Φ≦ 0.35mm	5
		Φ > 0.35mm	Reject



11.3.4.3	Air bubbles		
		Diameter (mm)	Acceptable Q'ty
		Φ≦ 0.2mm	Ignore
		0.2mm<Φ≦ 0.5mm	3
		Φ > 0.5mm	Reject
11.3.4.5	Scratch on		
	printing area	Size (mm)	Acceptable Q'ty
		W≦0.03mm, L≦5 mm	Ignore
		0.03mm <w≦0.05mm, l≦5mm<="" td=""><td>3</td></w≦0.05mm,>	3
		W>0.05mm or L> 5mm	Reject
		z	
		Size(mm)	Judgement
		X⊴2mm, Y≦2mm	Accept
		Z<1/2T	
		(T= single glass thickness)	
11.3.4.7	Edge chipping	x z	
		Size(mm)	Judgement
		X≦3 mm, Y≦3 mm	Accept
		Z≦1/2 T	
		(T= single glass thickness)	



12. Handling Precautions

12.1 Mounting method

The LCD panel of AMSON TFT module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

12.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[Recommended below] and wipe lightly

- Isopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns Do not use the following solvent on the pad or prevent it from being contaminated:

- Soldering flux
- Chlorine (CI), Sulfur (S)

If goods were sent without being silicon coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (CI), Sulfur (S) from customer, Responsibility is on customer.

12.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you:

Connect any unused input terminal to POWER or GROUND, do not input any signals before power is turned on, and ground your body, work/assembly areas, and assembly equipment to protect against static electricity.

12.4 packing

- Module employs LCD elements and must be treated as such.
- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity

12.5 Caution for operation

- It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.
- An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- Slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the maximum operating temperature, 50%Rh or less is required.





12.6 storing

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it . And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.
 [It is recommended to store them as they have been contained in the inner container at the time of delivery from us

12.7 Safety

- It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water

13. Precaution for Use

13.1

A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

13.2

On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification.
- When a new problem is arisen which is not specified in this specifications?
- When an inspection specifications change or operating condition change in customer is reported to AMSON TFT and some problem is arisen in this specification due to the change.
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

14. Packing Method TBD